

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2597593

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	KALYAN DAS	10/29/2013
RECEIVING PARTY DATA		
Name:	FUTUREWEI TECHNOLOGIES, INC.	
Street Address:	5340 LEGACY DRIVE	
Internal Address:	SUITE 175	
City:	PLANO	
State/Country:	TEXAS	
Postal Code:	75024	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	14067577
CORRESPONDENCE DATA		
Fax Number:	(408)938-9069	
Phone:	408-938-9060	
Email:	cholland@mhbpatents.com	
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>		
Correspondent Name:	FUTUREWEI TECHNOLOGIES, INC C/O MURABITO	
Address Line 1:	TWO NORTH MARKET STREET, THIRD FLOOR	
Address Line 4:	SAN JOSE, CALIFORNIA 95113	
ATTORNEY DOCKET NUMBER:	HW-91005030US01	
NAME OF SUBMITTER:	JAMES P. HAO	
Signature:	/James P. Hao/	
Date:	10/30/2013	
Total Attachments: 1 source=HW-91005030US01_Assignment#page1.tif		

OP \$40.00 14067577

Assignment to FUTUREWEI TECHNOLOGIES, INC.

In consideration of good and valuable consideration, receipt of which is hereby acknowledged, I/we
Kalyan DAS

do hereby sell, assign, and transfer unto FUTUREWEI TECHNOLOGIES, INC., a Texas Corporation having its principal place of business at 5340 Legacy Drive, Suite 175, Plano, TX 75024, USA, and its successors and assigns, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements, including the right of priority in, to, and under, the application for the United States patent entitled:

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filed herewith and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore; or

Serial No.: _____ filed on _____ and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore;

And for the above consideration, I/we agree promptly upon request of FUTUREWEI TECHNOLOGIES, INC, its successors or assigns, to execute and deliver without further compensation any power of attorney, assignment, application, whether original, continuation, divisional or reissue, or other papers which may be necessary or desirable fully to secure to FUTUREWEI TECHNOLOGIES, INC, its successors and assigns, the inventions described in said application and all patent rights therein, in the United States and in any country foreign thereto, and to cooperate and assist in the prosecution of interference proceedings involving said inventions and in the adjudication or reexamination of said Letters Patent provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by FUTUREWEI TECHNOLOGIES, INC.

I/we further covenant with FUTUREWEI TECHNOLOGIES, INC, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned;

Inventor's Signature: Kalyan DAS Date: 10/29/2013
Kalyan DAS